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TITLE: Printed wiring board manufacture involves forming circuit pattern by subtractive procedure and electrically connecting inner conductor layer and external insulating layer through formed via hole

PATENT-ASSIGNEE:

ASSIGNEE

CODE

NCI DENSHI KK

NCIDN

NIPPON CARBIDE KOGYO KK

NICA

PRIORITY-DATA: 1998JP-0335857 (November 26, 1998)

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE	PAGES	MAIN-IPC
JP <u>2000165047</u> A	June 16, 2000		006	H05K003/46

APPLICATION-DATA:

PUB-NO	APPL-DATE	APPL-NO	DESCRIPTOR
JP2000165047A	November 26, 1998	1998JP-0335857	

INT-CL (IPC): G01 B 11/00; H05 K 1/02; H05 K 3/00; H05 K 3/46

ABSTRACTED-PUB-NO: JP2000165047A

BASIC-ABSTRACT:

NOVELTY - The method involves forming a circuit pattern through subtractive procedure and electrical connection of inner conductor layer (12) and external conductor layer through a via hole (16). The via hole is formed by removing a portion of the external conductor layer and external insulating layer (13) using laser beam.

DETAILED DESCRIPTION - The external insulating layer and external conductor layer are laminated on a core base material (5) on which the circuit pattern and a recognition mark (4) are formed. The external conductor layer is formed in uniform thin layer. A recognition apparatus is used to read the recognition mark.

USE - None given.

ADVANTAGE - Ensures high quality reliability and high yield, and reduced positional offset when forming circuit pattern to ensure highly accurate manufacture of printed wiring board.

DESCRIPTION OF DRAWING(S) - The figure shows a sectional view of the manufactured printed wiring board.

Recognition mark 4

Core base material 5

Inner conductor layer 12